IXYS

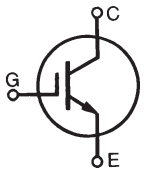
Advance Technical Data

HiPerFAST™ IGBT

IXGP 30N60B2

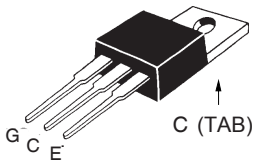
V_{CES} = 600 V
I_{C25} = 70 A
$V_{CE(sat)}$ < 1.8 V
$t_{fi\,typ}$ = 82 ns

Optimized for 10-25 KHz hard switching and up to 150 KHz resonant switching



Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C; R_{GE} = 1 MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C (limited by leads)	70	A
I_{C110}	T_C = 110°C	30	A
I_{CM}	T_C = 25°C, 1 ms	150	A
SSOA (RBSOA)	V_{GE} = 15 V, T_{VJ} = 125°C, R_G = 10 Ω Clamped inductive load @ ≤ 600 V	I_{CM} = 60	A
P_C	T_C = 25°C	190	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C
M_d	Mounting torque	1.13/10	Nm/lb.in.
Weight		4	g

TO-220 (IXSP)



G = Gate, C = Collector,
E = Emitter, TAB = Collector

Features

- Medium frequency IGBT
- Square RBSOA
- High current handling capability
- MOS Gate turn-on
  - drive simplicity

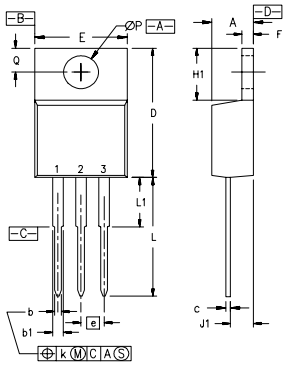
Applications

- PFC circuits
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies
- AC motor speed control
- DC servo and robot drives
- DC choppers

Symbol	Test Conditions		Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
$V_{GE(th)}$	I_C = 250 μA, V_{CE} = V_{GE}		2.5		5.0	V
I_{CES}	V_{CE} = V_{CES} V_{GE} = 0 V	T_J = 25°C T_J = 150°C			50 1	μA mA
I_{GES}	V_{CE} = 0 V, V_{GE} = ±20 V				±100	nA
$V_{CE(sat)}$	I_C = 24 A, V_{GE} = 15 V	T_J = 25°C			1.8	V

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Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	min.	typ.	max.	
g_{fs}	I_C = 24 A; V_{CE} = 10 V, Pulse test, t ≤ 300 µs, duty cycle ≤ 2 %	18	26		S
C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz		1500		pF
C_{oes}			115		pF
C_{res}			40		pF
Q_g	I_C = 24 A, V_{GE} = 15 V, V_{CE} = 300 V		66		nC
Q_{ge}			9		nC
Q_{gc}			22		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		13		ns
t_{ri}	I_C = 24 A, V_{GE} = 15 V		15		ns
$t_{d(off)}$	V_{CE} = 400 V, R_G = 5 Ω		110	200	ns
t_{fi}			82	150	ns
E_{off}			0.32	0.6	mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		13		ns
t_{ri}	I_C = 24 A, V_{GE} = 15 V		17		ns
E_{on}	V_{CE} = 400 V, R_G = 5 Ω		0.22		mJ
$t_{d(off)}$			200		ns
t_{fi}			150		ns
E_{off}			0.9		mJ
R_{thJC}				0.65	K/W
R_{thCH}			0.25		K/W



Pins: 1 - Gate 2 - Drain
3 - Source 4 - Drain

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343 6,583,505 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1 6,683,344

Fig. 1. Output Characteristics @ 25 Deg. C

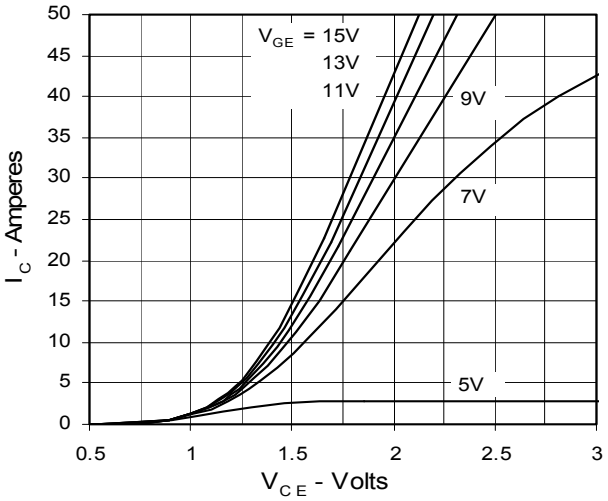


Fig. 2. Extended Output Characteristics @ 25 deg. C

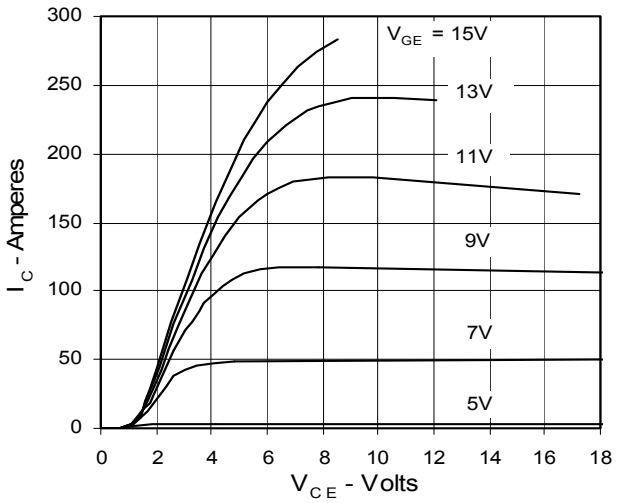


Fig. 3. Output Characteristics @ 125 Deg. C

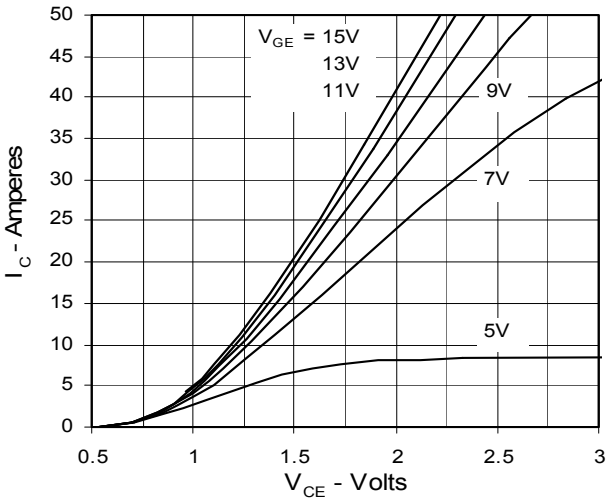


Fig. 4. Dependence of $V_{CE(sat)}$ on Temperature

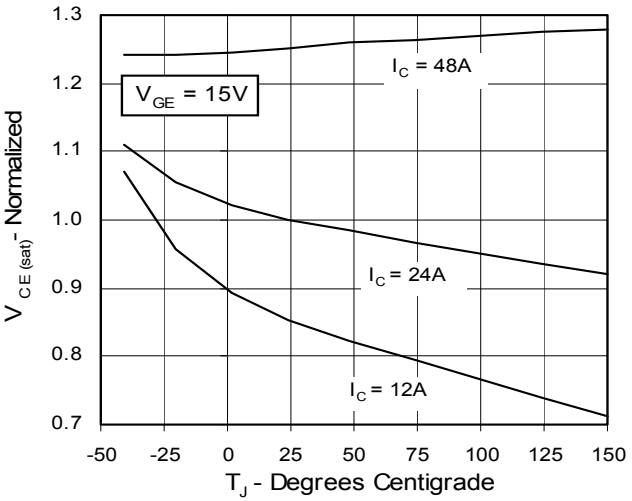


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter voltage

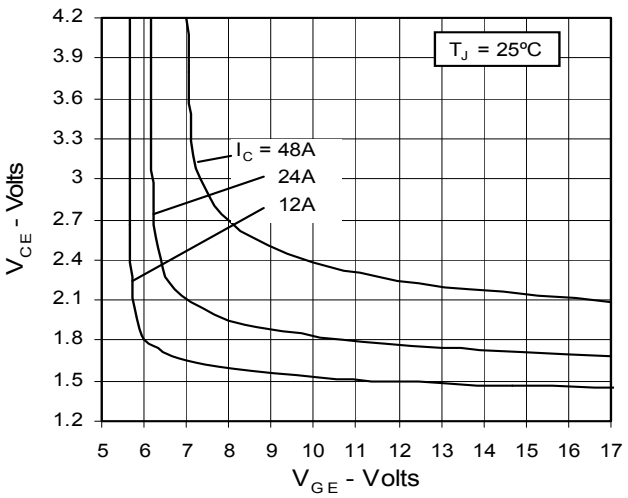
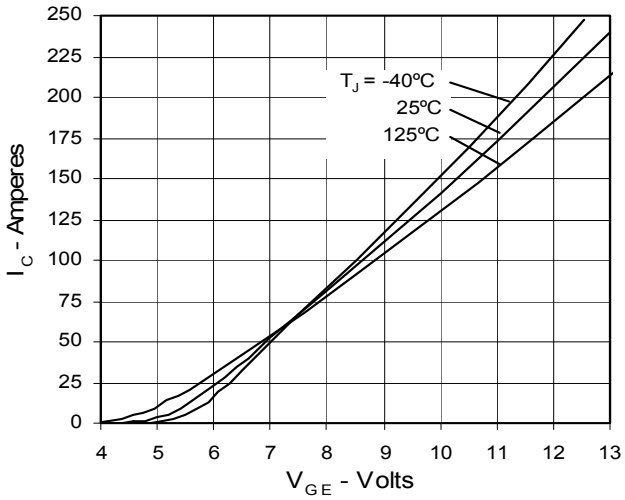


Fig. 6. Input Admittance



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Fig. 7. Transconductance

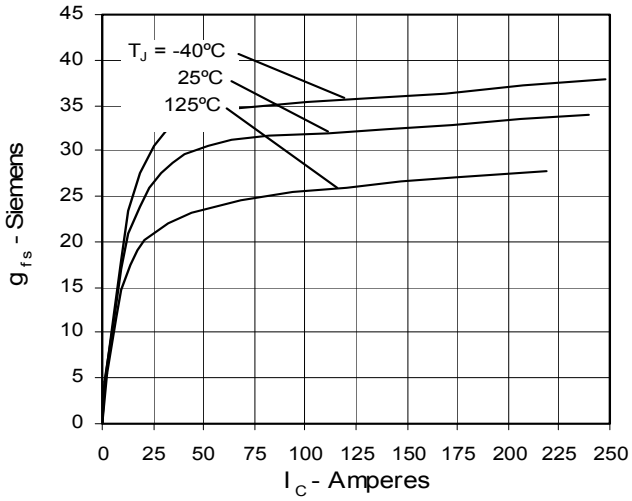


Fig. 8. Dependence of Turn-Off Energy on R_G

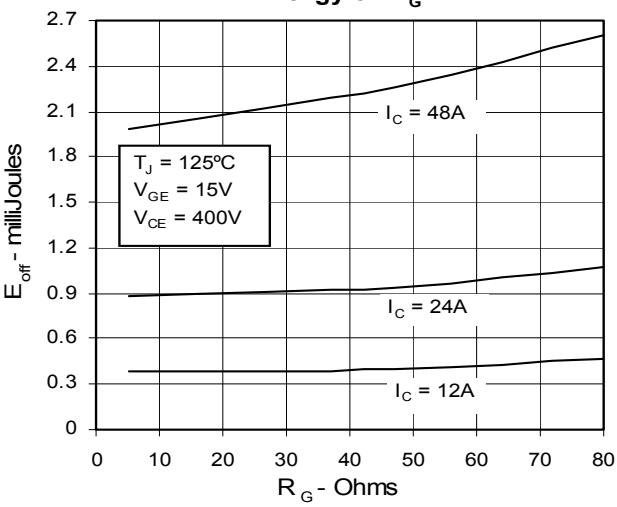


Fig. 9. Dependence of Turn-Off Energy on I_C

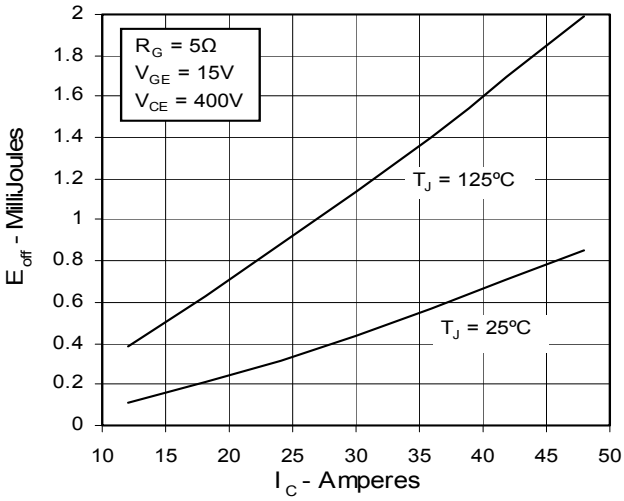


Fig. 10. Dependence of Turn-Off Energy on Temperature

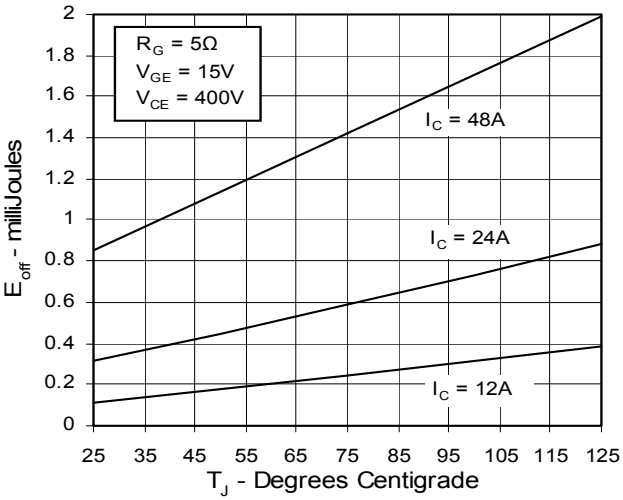


Fig. 11. Dependence of Turn-Off Switching Time on R_G

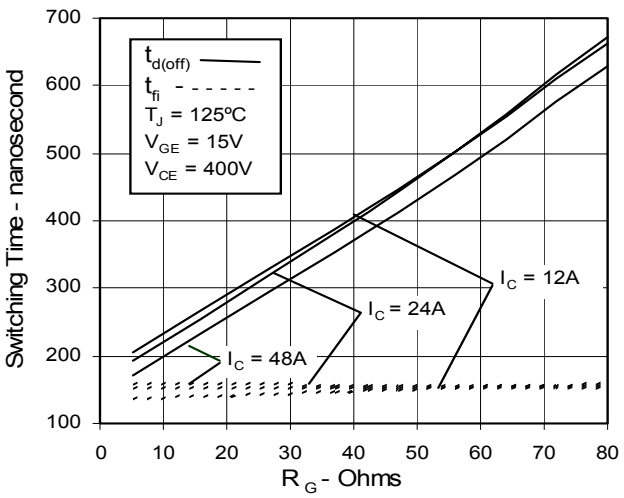
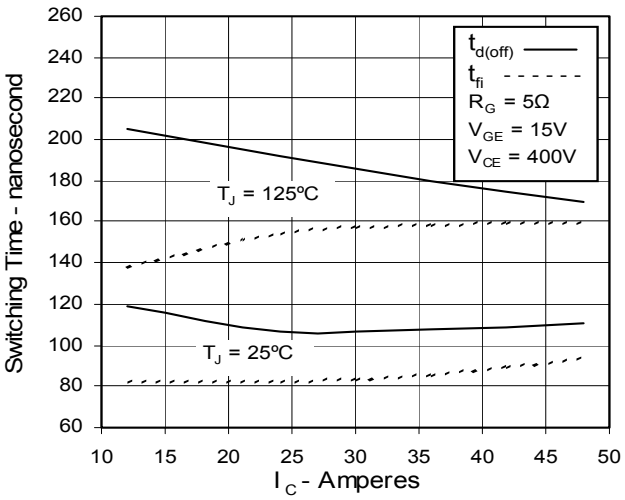


Fig. 12. Dependence of Turn-Off Switching Time on I_C



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Fig. 13. Dependence of Turn-Off Switching Time on Temperature

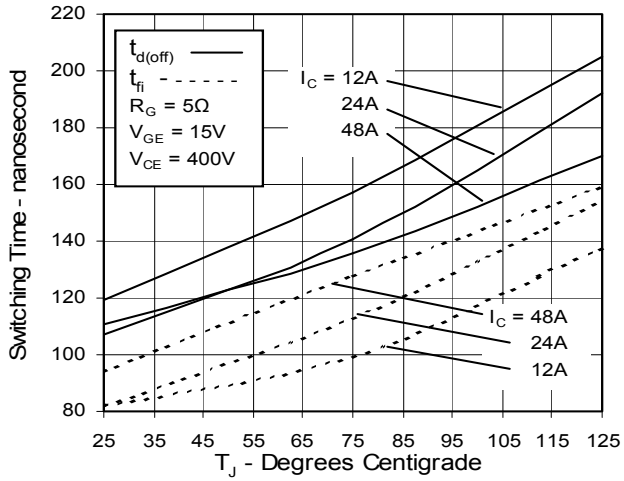


Fig. 14. Gate Charge

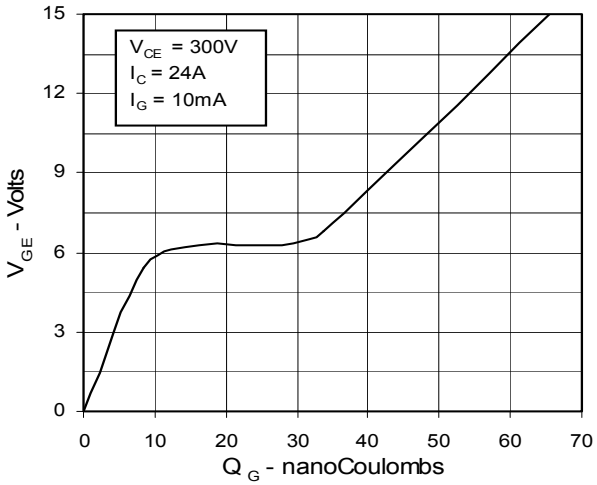


Fig. 15. Capacitance

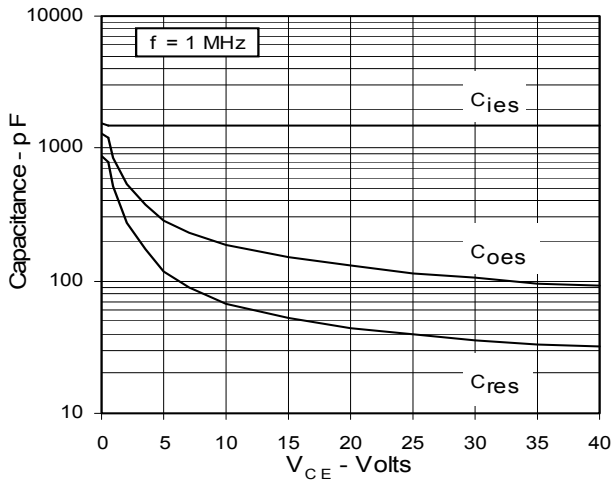
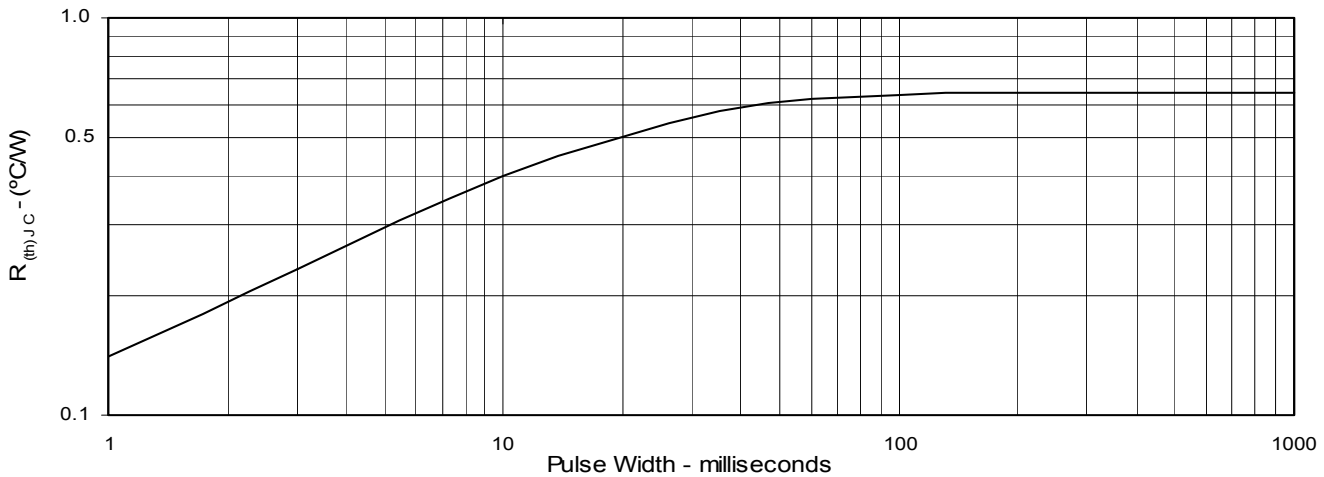


Fig. 16. Maximum Transient Thermal Resistance



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